



Instituto Nacional
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INTI

Extensión y Desarrollo
División Biblioteca

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Table of Contents

Introduction

I. Preface	7
II. History and organization	8
III. Interaction with educational institutions and research laboratories	10
IV. Doctoral research at IMEC	12
V. Interaction with industry and other research institutions	12
VI. Flanders, an attractive and dynamic location for new IT-driven industrial activities	17
VII. Logistics	21

Part I: Research at IMEC

Technology development and process integration for integrated circuits, microcomponents and photovoltaics

I.1. General introduction	26
I.2. Pilot lines	29
I.2.1. Introduction	29
I.2.2. Silicon pilot line	29
I.2.3. Solar cells pilot line	30
I.3. Silicon process development and integration	30
I.3.1. Introduction	30
I.3.2. CMOS processes	31
I.3.3. Non-volatile memory technology	36
I.3.4. BiCMOS technology	42
I.3.5. Mixed analog/digital CMOS	44
I.3.6. Novel silicon devices	46
I.4. Process steps and modules	50
I.4.1. Introduction	50
I.4.2. Lithography	50
I.4.3. Dry etching	56
I.4.4. Lateral isolation	58
I.4.5. Ultra clean processing	60
I.4.6. ES&H and in-situ gas analysis	63
I.4.7. Advanced high-k dielectrics and metal gates for sub-100 nm devices	64
I.4.8. Silicidation and shallow junction formation	68
I.4.9. Si and Si _{1-x} Ge _x epitaxy	69
I.4.10. Chemical mechanical polishing	71
I.4.11. Low-k dielectrics and Cu interconnections	72

1.5. Modeling and characterization	76
1.5.1. Introduction	76
1.5.2. TCAD	76
1.5.3. CMOS reliability and yield	78
1.5.4. Materials and components analysis	82
1.5.5. Characterization for special applications	85
1.6. Systems-in-a-package	87
1.6.1. Introduction	87
1.6.2. RF systems-in-a-package	88
1.6.3. Optical systems-in-a-package	92
1.6.4. Detector systems-in-a-package	95
1.6.5. Magneto systems-in-a-package	98
1.6.6. Biosensors and molecular nanotechnology	101
1.6.7. High-density interconnection and packaging technology	104
1.6.8. Micro-electromechanical systems	108
1.6.9. Microsystems reliability	112
1.7. Photovoltaics	112
1.7.1. Introduction	112
1.7.2. Industrial solar cells	112
1.7.3. Advanced solar cells	115
1.8. Plastic electronics	117
1.8.1. Introduction	117
1.8.2. Device research	117

Digital telecom systems, design methods, design training

II.1. General introduction	120
II.2. Integrated telecommunication systems	121
II.2.1. Introduction	121
II.2.2. Broadband OFDM wireless indoor networks	122
II.2.3. Reconfigurable information appliances	125
II.3. Advanced multimedia applications	127
II.3.1. Introduction	127
II.3.2. Quality-of-service (QoS)	128
II.3.3. Cost-efficient implementations of multimedia systems	129
II.4. Design technology for embedded systems	132
II.4.1. Introduction	132
II.4.2. Executable system modeling and refinement	132
II.4.3. Data and memory management	136
II.4.4. RF and mixed-signal design methodologies	143

II.5. Industrial training and multichip services for academia & industry	146
II.5.1. Introduction	146
II.5.2. The microelectronics training center	147
II.5.3. Threshold lowering design activities	147
II.5.4. Deep submicron layout service	149
II.5.5. EURO PRACTICE: ASIC prototype and small-volume fabrication	150
References	152

Part 2: Research at university groups, done in collaboration with IMEC

Universiteit Gent (RUG)

I. General introduction	208
II. High-frequency and high-speed (HFHS)	208
II.1. Introduction	208
II.2. Training hardware design engineers at INTEC design	209
II.3. High-frequency and high-speed modeling and characterization	212
III. Optoelectronics	215
III.1. Introduction	215
III.2. Epitaxial growth, processing and packaging technology	215
III.3. CAD and measurement tools	218
III.4. Photonic components	218
III.5. Optoelectronic systems	222
IV. Telecommunication systems	224
IV.1. Introduction	224
IV.2. Broadband communication networks	224
IV.3. Formal methods in system modeling	226
V. Hardware system integration	226
V.1. Introduction	226
V.2. Interconnection systems	227
V.3. Microdisplay systems	230
VI. Design activities	231
VI.1. Optical interconnections in electronic circuits	231
VI.2. Specific CMOS circuit designs	232
VII. Luminescent films	233
VII.1. Introduction	233
VII.2. Electroluminescent films	233
VII.3. Cathodoluminescent films	233
References	234

Vrije Universiteit Brussel (VUB)

I. General introduction	254
II. Laboratory for micro- & optoelectronics (LAMI)	254
III. Laboratory for information retrieval and information sciences (IRIS)	259
IV. Laboratory for microwave microelectronic measurements & modeling (4M)	268
References	269

Katholieke Universiteit Leuven (K.U.Leuven)

ESAT Laboratory

I. Application-driven configuring of computing architectures (ACCA)	276
II. Electrical energy (ELEN)	278
III. Microelectronics and sensors (MICAS)	285
IV. Center for processing speech and images (PSI)	286
V. Signals, identification, system theory and automation (SISTA)	288
VI. Telecommunications and microwaves (TELEMIC)	290
References	293

Universiteit Antwerpen (UA)

I. Experimental condensed matter physics (ECM)	299
II. Electrical transport in low-dimensional structures	303
III. Micro- and trace analysis center (MiTAC)	305
IV. Structural chemistry	307
V. Quantum transport in nanostructures	308
References	310

Limburgs Universitair Centrum (LUC)

Institute of Materials Research (IMO)

I. Materials physics division	315
II. Materials chemistry division	318
References	319

List of funded research projects (RP)	320
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List of collaborative projects with universities located in Flanders (UP)	327
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List of abbreviations	331
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Organization IMEC	334
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